PRODUCT CHANGE NOTICE		
PART NUMBER(S):	PCN No.: 06-0130-11a	
Please see attachment.	DATE: March 7, 2006	
PART DESCRIPTION:		
Power Management and Interface Products – Change in Wafer Fabrication Site		
LEVEL OF CHANGE:		
[X] Level I, Customer Approval.	[] Level II, Customer Information.	
PRODUCT ATTRIBUTE AFFECTED:		
[] Material Change [] Design Change [X] Process Change	[] Data Sheet Change[] Package Change[] Packing / Shipping	
[X] Other, Explain: Wafer Fabrication Site Transfer		
DESCRIPTION OF CHANGE:		
Announcing transfer of certain Power Management and Interface Products from Hillview wafer fabrication facility to wafer foundry Silan. See attached Product List no. 11a		
REASON FOR CHANGE:		
Power Management and Interface products as listed are being transferred to external wafer foundry, due to cessation of operations of the Sipex Hillview Wafer Fabrication manufacturing site.		
FABRICATION PROCESS QUALIFICATION COMPLETED (DATE): 5/28/06	PRODUCT CHARACTERIZATION COMPLETED AND SAMPLES* AVAILABLE (DATE): 7/14/06	

^{*} Samples representative of product from the Product Family being transferred.



PRODUCT	CHANGE NOTICE
EARLIEST DATE OF PRODUCTION SHIPMENTS: 10/23/06	
EFFECTIVITY CHANGE DATE OR DATE CODE	: Work week associated with earliest production shipment.
[] STANDARD DISTRIBUTION	[X] CUSTOM DISTRIBUTION
PERSON TO CONTACT WITH QUESTIONS:	
Fred Claussen	
VP Quality Assurance and Reliability Sipex Corporation Phone Number: 408-935-7644 FAX NUMBER: 408-935-7678	



PRODUCT CHANGE NOTICE

PCN No.: 06-0130-11a

List 11a

SP3070EEN

SP3070EEN-L

SP3070EMN

SP3070EMN-L

SP3071EEN

SP3071EEN-L

SP3071EMN

SP3071EMN-L

SP3073EEN

SP3073EEN-L

SP3073EMN

SP3073EMN-L

SP3074EEN

SP3074EEN-L

SP3074EMN

SP3074EMN-L

SP3076EEN

SP3076EEN-L

SP3076EMN

SP3076EMN-L

SP3077EEN

SP3077EEN-L

SP3077EMN

SP3077EMN-L

SP3072EEN

SP3072EEN-L

SP3072EMN

SP3072EMN-L

SP3075ECN-L

SP3075EEN

SP3075EEN-L

SP3075EMN SP3075EMN-L

SP3078EEN

SP3078EEN-L

SP3078EMN

SP3078EMN-L